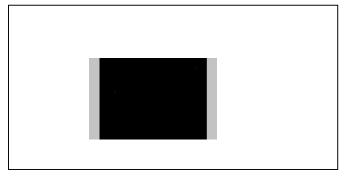
ethertronics*

PRODUCT SPEC SHEET: BLUETOOTH™ ANTENNA

Part No. 1001312

Embedded Bluetooth™ Ceramic Antenna 2.4 GHz, 2.0x1.2mm



Ethertronics' series of BT Ceramic Antennas deliver on the key needs of device designers for higher functionality and performance in smaller/thinner designs. These innovative antennas provide compelling advantages for Bluetooth enabled cell phones, media players and other mobile devices.



Best in Class Performance

- Minimal ground clearance and component "keep out" area.
- High selectivity eliminates the need for additional filters and frees up board space.

Quicker Time-to-Market

- Standard part means fewer design changes.
- Simple implementation.
- Single part works for various PCB sizes and layouts.

RoHS Compliant

• Ethertronics' antennas comply with the European RoHS Directive 2002/95/EC.



KEY BENEFITS

END USER ADVANTAGES

Superior Range

 Greater antenna efficiency means longer range and a better end user experience.

Exceptional Coverage

 Better coverage delivers more reliable wireless connections for mobile phones, laptops, stereo headsets, cars media players, audio systems and more.

SERVICE AND SUPPORT

Extensive RF Experience

 Our antennas are supported by extensive documentation, and when needed, by the expertise of RF engineers who have integrated hundreds of antenna designs into wireless devices.

Global Operations & Design Support

 Ethertronics' global operations encompass an integrated network of design centers that provide local customer support.

More information is available on our Website at www.ethertronics.com/resources/.

Ethertronics' Embedded BT Ceramic Antenna Specifications
Ethertronics produces a wide variety of standard and custom antennas to meet user needs.

Below are the typical specs for a BT application.

Electrical Specifications

Typical Characteristics

All values are defined at

Pi matching circuit will be required

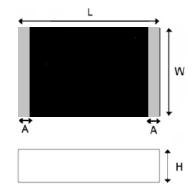
*Test board size = 110x55mm ground plane.

BT Antenna	Specifications
Frequency Band	2.400GHz~2.483GHz
VSWR	Less than 3
Polarization	Linear
*Peak Gain	1.72 dBi Typ.
*Peak Efficiency	72.3% Typ
Impedance	50Ω Typ.

Mechanical Specifications

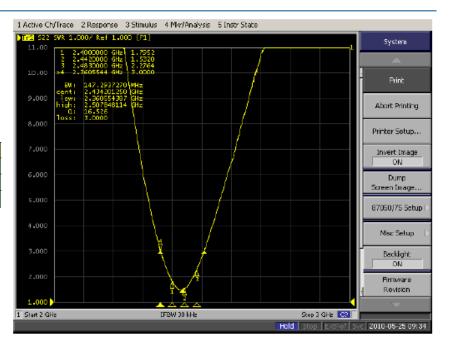
Size	2.00x1.20x0.55mm
Mounting	Surface Mount

L W		Н	А
2.0±0.3	1.2±0.3	.55±0.2	0.4±0.25

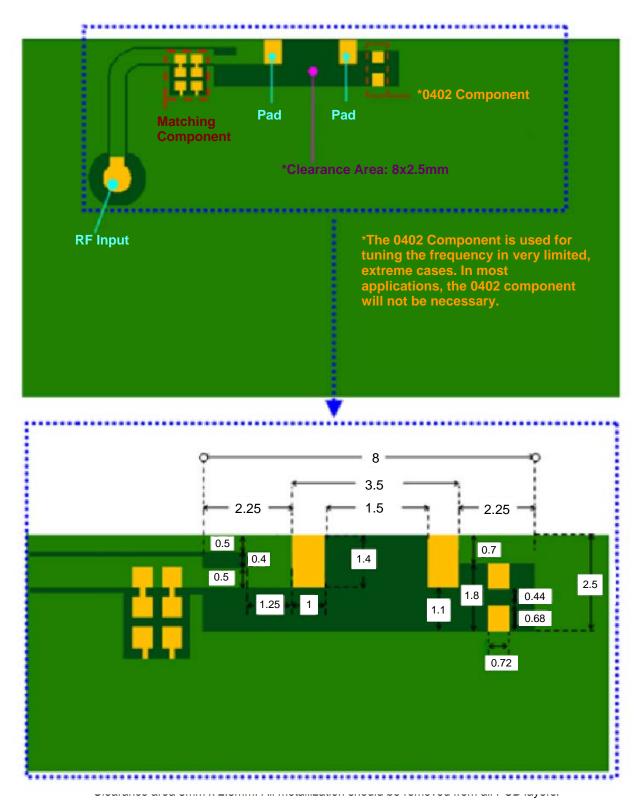


VSWR

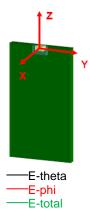
Mark	Frequency	VSWR
1	2400 MHz	1.80
2	2442 MHz	1.53
3	2483 MHz	2 28

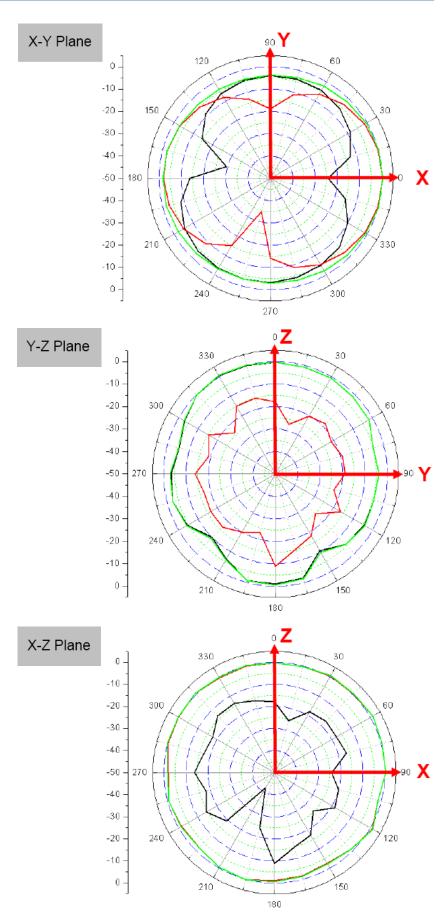


Recommended PCB Layout (Unit = mm)



2D Gain Patterns (2442 MHz)





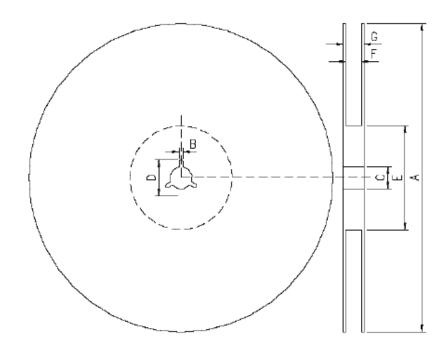
Tape & Reel Specifications

Quantity/Reel = 5,000

Unit = mm

F
E

А	В	С	D	E	F	L	W
8.00±0.30	3.5±0.05	1.75±0.10	2.00±0.05	4.00±0.10	1.50±0.10	2.30±0.10	1.55±0.10



Top Tape

Symbol	Spec.
Α	178.0±2.0
В	2.0±0.5
С	13.0±0.5
D	21.0±0.8
E	62.0±1.5
F	9.0±0.5
G	13.0±1.0

Reliability Testing

Item	Condition	Specification	
Thermal Shock	 30±3 minutes at -40°C±5°C Convert to +105°C (5 minutes) 30±3 minutes at +105°C±5°C Convert to -40°C (5 minutes) Total: 100 continuous cycles 	No apparent damage. Fulfills the electrical spec after test.	
Humidity Resistance	 Humidity: 85% R.H. Temperature: 85±5°C Time: 1,000 hours 	No apparent damage. Fulfills the electrical spec after test.	
High Temperature Resistance	 Temperature: 150°C±5°C Time: 1,000 hours 	No apparent damage. Fulfills the electrical spec after test.	
Low Temperature Resistance	 Temperature: -40°C±5°C Time: 1,000 hours 	No apparent damage. Fulfills the electrical spec after test.	
Soldering Heat Resistance	 Solder bath temperature: 260±5°C Bathing time: 10±1 seconds 	No apparent damage.	
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after being dipped in a solder bath of 245±5°C for 3±1 seconds	No apparent damage.	

Storage Conditions

Warehouse Temperature Range:

The temperature should be within 0~30°C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery

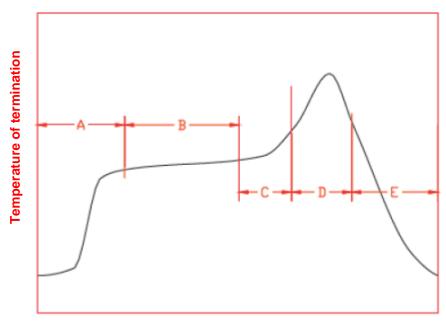
On Board Temperature Range:

The temperature should be within -40~85°C and humidity should be less than 85% RH.

Operating Temperature Range

Operating temperature range: -40°C to +105°C

Recommended Reflow Soldering



Time

Α	1 st Rising Temperature	The normal to preheating temperature	30s to 60s		
В	Preheating	140°C to 160°C	60s to 120s		
С	2 nd Rising Temperature	Preheating to 200°C	20s to 40s		
D	Main Heating	if 220°C	50s~60s		
		if 230°C	40s~50s		
		if 240°C	30s~40s		
		if 250°C	20s~40s		
		if 260°C	20s~40s		
Е	Regular Cooling	200°C to 100°C	1°C /s ~ 4°C /s		
*refer	*reference: J-STD-020C				

Soldering Gun Procedure

Note the following when using a solder gun to replace the antenna

- 1. The tip temperature must be less than 350°C for the period within 3 seconds when using a soldering gun under 30W.
- 2. The soldering gun tip shall not touch this part directly.

Soldering Volume

Note that excess of soldering volume will easily crach the body of this product.